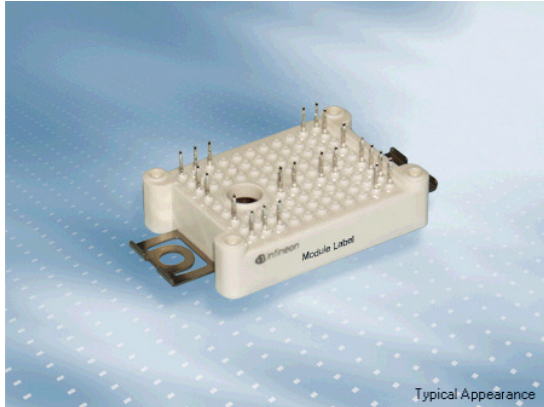
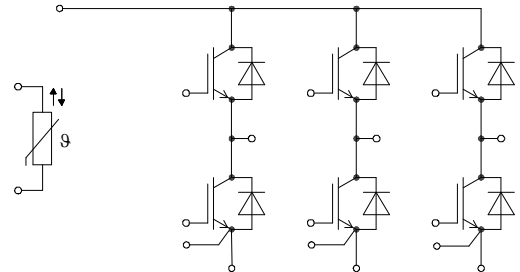


EasyPACK Modul mit Trench/Feldstopp IGBT3 und Emitter Controlled 3 Diode und PressFIT / NTC
EasyPACK module with Trench/Fieldstop IGBT3 and Emitter Controlled 3 diode and PressFIT / NTC



Typical Appearance



$V_{CES} = 650V$
 $I_{C\ nom} = 50A / I_{CRM} = 100A$

Typische Anwendungen

- Hybrid-Elektrofahrzeuge (H)EV
- Klimaanlage
- Motorantriebe

Typical Applications

- Hybrid Electrical Vehicles (H)EV
- Air Conditioning
- Motor Drives

Elektrische Eigenschaften

- Erhöhte Sperrspannungsfestigkeit auf 650V
- Niedrige Schaltverluste
- Niedriges V_{CEsat}
- Trench IGBT 3

Electrical Features

- Increased blocking voltage capability to 650V
- Low Switching Losses
- Low V_{CEsat}
- Trench IGBT 3

Mechanische Eigenschaften

- Al_2O_3 Substrat mit kleinem thermischen Widerstand
- Hohe Leistungsdichte
- Integrierter NTC Temperatur Sensor
- Kompaktes Design
- PressFIT Verbindungstechnik
- RoHS konform
- Robuste Montage durch integrierte Befestigungsklammern

Mechanical Features

- Al_2O_3 Substrate with Low Thermal Resistance
- High Power Density
- Integrated NTC temperature sensor
- Compact design
- PressFIT Contact Technology
- RoHS compliant
- Rugged mounting due to integrated mounting clamps

Module Label Code

Barcode Code 128



DMX - Code



Content of the Code

| | Digit |
|----------------------------|---------|
| Module Serial Number | 1 - 5 |
| Module Material Number | 6 - 11 |
| Production Order Number | 12 - 19 |
| Datecode (Production Year) | 20 - 21 |
| Datecode (Production Week) | 22 - 23 |

| | | |
|-----------------|---------------------------------|--------------------|
| prepared by: SS | date of publication: 2012-01-12 | material no: 35374 |
| approved by: TR | revision: 3.0 | |

IGBT-Wechselrichter / IGBT-inverter

Höchstzulässige Werte / Maximum Rated Values

| | | | | |
|--|--|-----------------------------|----------|--------|
| Kollektor-Emitter-Sperrspannung Collector-emitter voltage | $T_{vj} = 25^{\circ}\text{C}$ | V_{CES} | 650 | V |
| Kollektor-Dauergleichstrom Continuous DC collector current | $T_C = 90^{\circ}\text{C}, T_{vj} = 175^{\circ}\text{C}$ $T_C = 25^{\circ}\text{C}, T_{vj} = 175^{\circ}\text{C}$ | $I_{C\text{ nom}}$ I_C | 50 70 | A A |
| Periodischer Kollektor-Spitzenstrom Repetitive peak collector current | $t_p = 1\text{ ms}$ | I_{CRM} | 100 | A |
| Gesamt-Verlustleistung Total power dissipation | $T_C = 25^{\circ}\text{C}, T_{vj} = 175^{\circ}\text{C}$ | P_{tot} | 205 | W |
| Gate-Emitter-Spitzenspannung Gate-emitter peak voltage | | V_{GES} | +/-20 | V |

Charakteristische Werte / Characteristic Values

| | | | min. | typ. | max. | |
|---|--|---|---------------------|-------------------------|------|---|
| Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage | $I_C = 50\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 50\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 50\text{ A}, V_{GE} = 15\text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | $V_{CE\text{ sat}}$ | 1,45 1,60 1,70 | 1,90 | V V V |
| Gate-Schwellenspannung Gate threshold voltage | $I_C = 0,80\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$ | | V_{GEth} | 4,9 5,8 | 6,5 | V |
| Gateladung Gate charge | $V_{GE} = -15\text{ V} \dots +15\text{ V}$ | | Q_G | 0,50 | | μC |
| Interner Gatewiderstand Internal gate resistor | $T_{vj} = 25^{\circ}\text{C}$ | | R_{Gint} | 0,0 | | Ω |
| Eingangskapazität Input capacitance | $f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$ | | C_{ies} | 3,10 | | nF |
| Rückwirkungskapazität Reverse transfer capacitance | $f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$ | | C_{res} | 0,095 | | nF |
| Kollektor-Emitter-Reststrom Collector-emitter cut-off current | $V_{CE} = 650\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$ | | I_{CES} | | 0,05 | mA |
| Gate-Emitter-Reststrom Gate-emitter leakage current | $V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$ | | I_{GES} | | 400 | nA |
| Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load | $I_C = 50\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 6,8\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | $t_{d\text{ on}}$ | 0,023 0,023 0,023 | | μs μs μs |
| Anstiegszeit, induktive Last Rise time, inductive load | $I_C = 50\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 6,8\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | t_r | 0,019 0,022 0,022 | | μs μs μs |
| Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load | $I_C = 50\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 6,8\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | $t_{d\text{ off}}$ | 0,17 0,19 0,20 | | μs μs μs |
| Fallzeit, induktive Last Fall time, inductive load | $I_C = 50\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 6,8\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | t_f | 0,03 0,04 0,05 | | μs μs μs |
| Einschaltverlustenergie pro Puls Turn-on energy loss per pulse | $I_C = 50\text{ A}, V_{CE} = 300\text{ V}, L_S = 50\text{ nH}$ $V_{GE} = \pm 15\text{ V}, di/dt = 2200\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $R_{Gon} = 6,8\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | E_{on} | 0,40 0,57 0,64 | | mJ mJ mJ |
| Abschaltverlustenergie pro Puls Turn-off energy loss per pulse | $I_C = 50\text{ A}, V_{CE} = 300\text{ V}, L_S = 50\text{ nH}$ $V_{GE} = \pm 15\text{ V}, du/dt = 4000\text{ V}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $R_{Goff} = 6,8\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ | E_{off} | 1,20 1,60 1,70 | | mJ mJ mJ |
| Kurzschlußverhalten SC data | $V_{GE} \leq 15\text{ V}, V_{CC} = 360\text{ V}$ $V_{CEmax} = V_{CES} - L_{sCE} \cdot di/dt$ | $t_p \leq 8\ \mu\text{s}, T_{vj} = 25^{\circ}\text{C}$ $t_p \leq 6\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$ | I_{SC} | 350 250 | | A A |
| Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case | pro IGBT / per IGBT | | R_{thJC} | 0,65 | 0,73 | K/W |
| Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink | pro IGBT / per IGBT $\lambda_{Paste} = 1\text{ W}/(\text{m}\cdot\text{K}) / \lambda_{grease} = 1\text{ W}/(\text{m}\cdot\text{K})$ | | R_{thCH} | 0,80 | | K/W |

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Diode-Wechselrichter / Diode-inverter
Höchstzulässige Werte / Maximum Rated Values

| | | | | |
|---|--|-----------|-----|----------------------|
| Periodische Spitzensperrspannung Repetitive peak reverse voltage | $T_{vj} = 25^{\circ}\text{C}$ | V_{RRM} | 650 | V |
| Dauergleichstrom Continuous DC forward current | | I_F | 50 | A |
| Periodischer Spitzenstrom Repetitive peak forward current | $t_p = 1 \text{ ms}$ | I_{FRM} | 100 | A |
| Grenzlastintegral I^2t - value | $V_R = 0 \text{ V}, t_p = 10 \text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0 \text{ V}, t_p = 10 \text{ ms}, T_{vj} = 150^{\circ}\text{C}$ | I^2t | 370 | A^2s |
| | | | 330 | A^2s |

Charakteristische Werte / Characteristic Values

| | | | min. | typ. | max. | |
|---|---|--------------------------------|-----------|------|------|---------------|
| Durchlassspannung Forward voltage | $I_F = 50 \text{ A}, V_{GE} = 0 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ | V_F | 1,55 | 2,00 | V |
| | $I_F = 50 \text{ A}, V_{GE} = 0 \text{ V}$ | $T_{vj} = 125^{\circ}\text{C}$ | | 1,50 | | V |
| | $I_F = 50 \text{ A}, V_{GE} = 0 \text{ V}$ | $T_{vj} = 150^{\circ}\text{C}$ | | 1,45 | | V |
| Rückstromspitze Peak reverse recovery current | $I_F = 50 \text{ A}, -di_F/dt = 2200 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300 \text{ V}$ $V_{GE} = -15 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ | I_{RM} | 50,0 | | A |
| | | $T_{vj} = 125^{\circ}\text{C}$ | | 60,0 | | A |
| | | $T_{vj} = 150^{\circ}\text{C}$ | | 65,0 | | A |
| Sperrverzögerungsladung Recovered charge | $I_F = 50 \text{ A}, -di_F/dt = 2200 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300 \text{ V}$ $V_{GE} = -15 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ | Q_r | 2,00 | | μC |
| | | $T_{vj} = 125^{\circ}\text{C}$ | | 3,90 | | μC |
| | | $T_{vj} = 150^{\circ}\text{C}$ | | 4,40 | | μC |
| Abschaltenergie pro Puls Reverse recovery energy | $I_F = 50 \text{ A}, -di_F/dt = 2200 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300 \text{ V}$ $V_{GE} = -15 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ | E_{rec} | 0,50 | | mJ |
| | | $T_{vj} = 125^{\circ}\text{C}$ | | 1,00 | | mJ |
| | | $T_{vj} = 150^{\circ}\text{C}$ | | 1,15 | | mJ |
| Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case | pro Diode / per diode | R_{thJC} | | 1,00 | 1,10 | K/W |
| Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink | pro Diode / per diode $\lambda_{\text{Paste}} = 1 \text{ W}/(\text{m}\cdot\text{K}) / \lambda_{\text{grease}} = 1 \text{ W}/(\text{m}\cdot\text{K})$ | R_{thCH} | | 0,85 | | K/W |

NTC-Widerstand / NTC-thermistor

Charakteristische Werte / Characteristic Values

| | | | min. | typ. | max. | |
|--|--|--------------|------|------|------|------------|
| Nennwiderstand Rated resistance | $T_C = 25^{\circ}\text{C}$ | R_{25} | | 5,00 | | k Ω |
| Abweichung von R100 Deviation of R100 | $T_C = 100^{\circ}\text{C}, R_{100} = 493 \Omega$ | $\Delta R/R$ | -5 | | 5 | % |
| Verlustleistung Power dissipation | $T_C = 25^{\circ}\text{C}$ | P_{25} | | | 20,0 | mW |
| B-Wert B-value | $R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$ | $B_{25/50}$ | | 3375 | | K |
| B-Wert B-value | $R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$ | $B_{25/80}$ | | 3411 | | K |
| B-Wert B-value | $R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$ | $B_{25/100}$ | | 3433 | | K |

Angaben gemäß gültiger Application Note.
Specification according to the valid application note.

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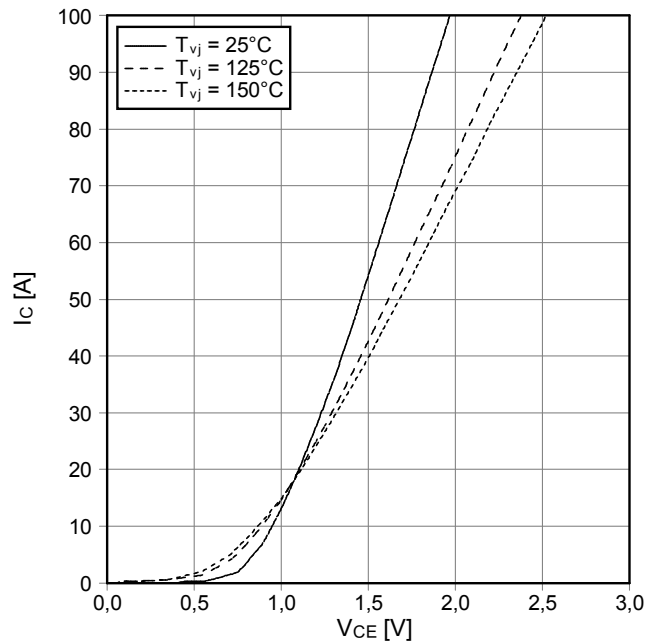
Modul / Module

| | | | | | |
|--|---|----------------------|--------------------------------------|------|--------|
| Isolations-Prüfspannung Isolation test voltage | RMS, f = 50 Hz, t = 1 min. | V _{ISOL} | 2,5 | | kV |
| Innere Isolation Internal isolation | | | impr. Al ₂ O ₃ | | |
| Kriechstrecke Creepage distance | Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal | | 11,5 6,3 | | mm |
| Luftstrecke Clearance | Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal | | 10,0 5,0 | | mm |
| Vergleichszahl der Kriechwegbildung Comperative tracking index | | CTI | > 200 | | |
| | | | min. | typ. | max. |
| Modulstreuintduktivität Stray inductance module | | L _{SCE} | | 25 | nH |
| Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip | T _C = 25°C, pro Schalter / per switch | R _{CC'+EE'} | | 3,50 | mΩ |
| Höchstzulässige Sperschichttemperatur Maximum junction temperature | Wechselrichter, Brems-Chopper / Inverter, Brake-Chopper | T _{vj max} | | | 175 °C |
| Temperatur im Schaltbetrieb Temperature under switching conditions | Wechselrichter, Brems-Chopper / Inverter, Brake-Chopper | T _{vj op} | -40 | | 150 °C |
| Lagertemperatur Storage temperature | | T _{stg} | -40 | | 125 °C |
| Anpresskraft für mech. Bef. pro Feder mounting force per clamp | | F | 20 | - | 50 N |
| Gewicht Weight | | G | | 24 | g |

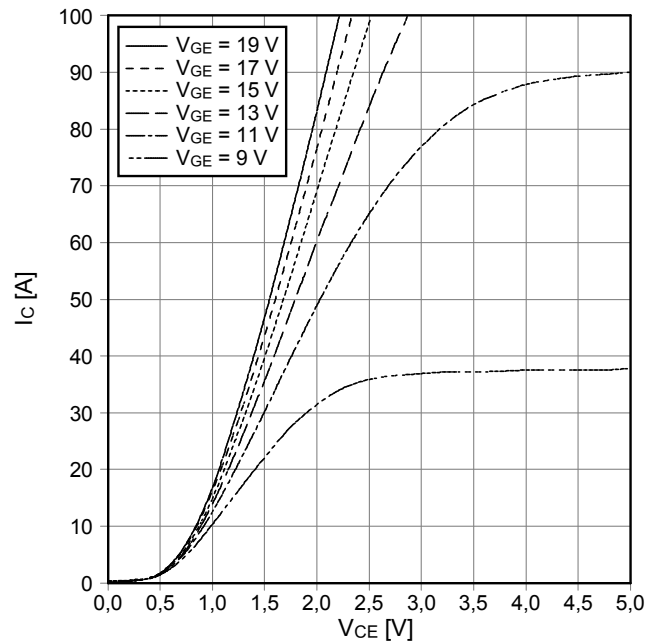
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| approved by: TR | revision: 3.0 |



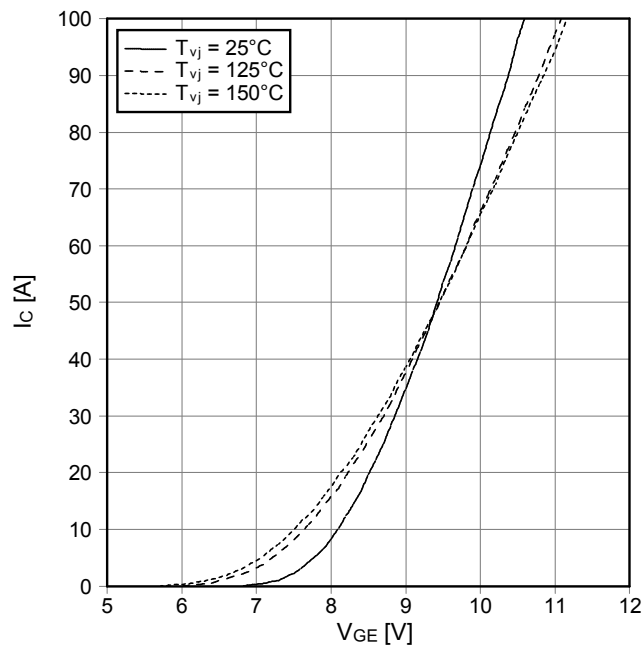
Ausgangskennlinie IGBT-Wechselr. (typisch)
output characteristic IGBT-inverter (typical)
 $I_c = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



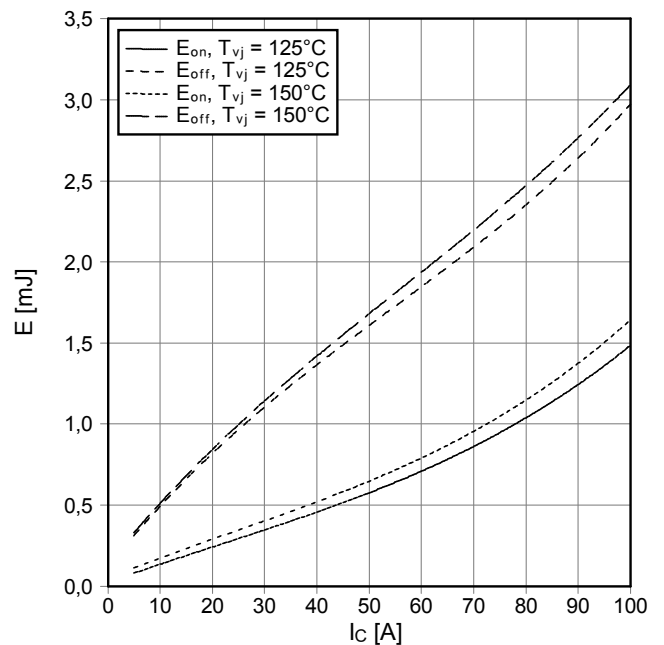
Ausgangskennlinienfeld IGBT-Wechselr. (typisch)
output characteristic IGBT-inverter (typical)
 $I_c = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



Übertragungscharakteristik IGBT-Wechselr. (typisch)
transfer characteristic IGBT-inverter (typical)
 $I_c = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



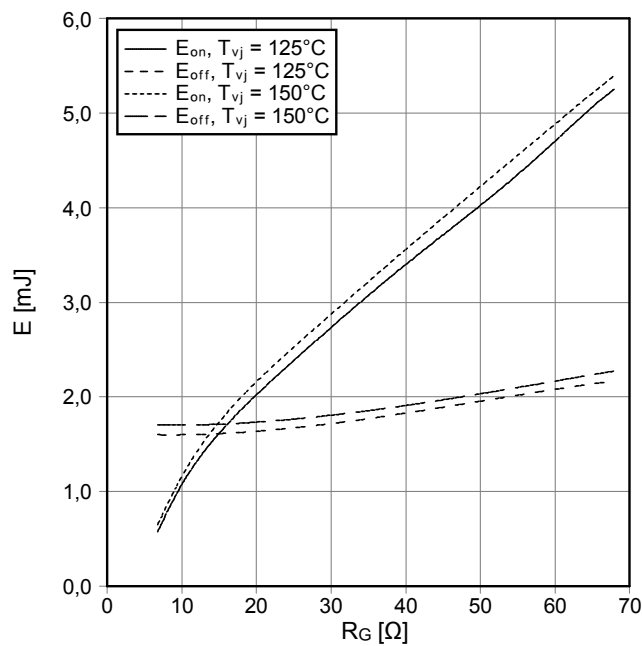
Schaltverluste IGBT-Wechselr. (typisch)
switching losses IGBT-inverter (typical)
 $E_{on} = f(I_c), E_{off} = f(I_c)$
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 6.8\ \Omega, R_{Goff} = 6.8\ \Omega, V_{CE} = 300\text{ V}$



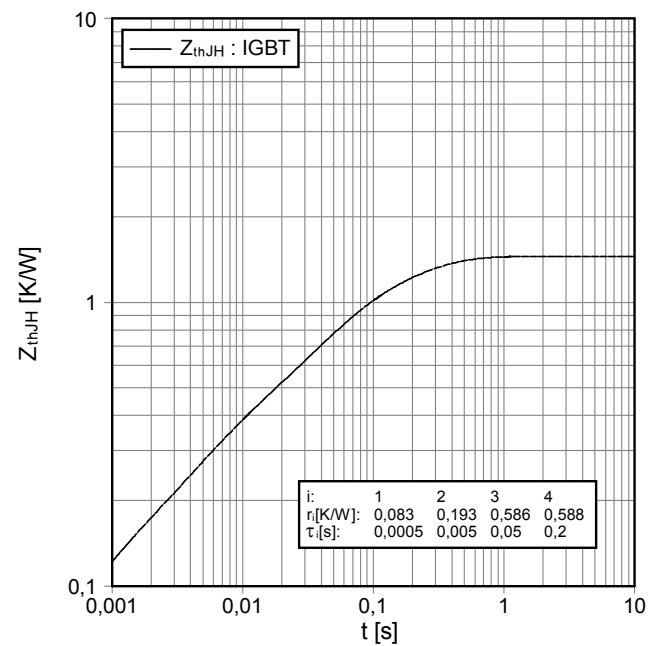
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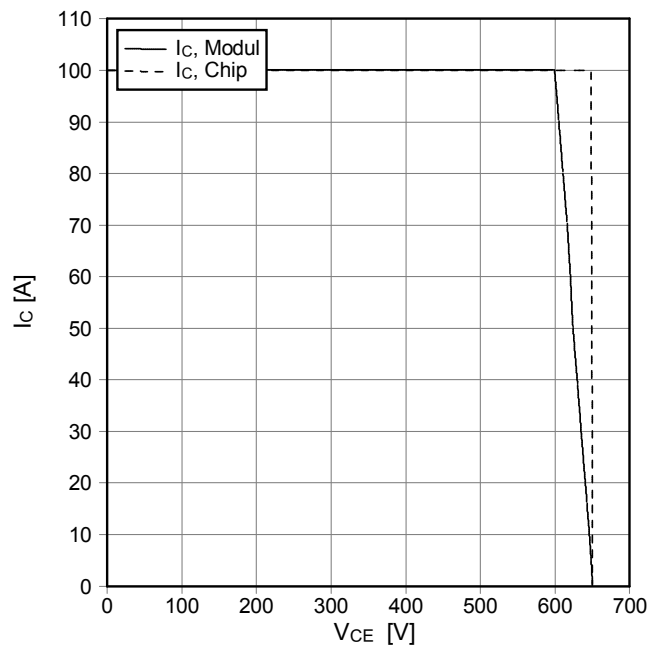
Schaltverluste IGBT-Wechselr. (typisch)
switching losses IGBT-inverter (typical)
 $E_{on} = f(R_G)$, $E_{off} = f(R_G)$
 $V_{GE} = \pm 15\text{ V}$, $I_C = 50\text{ A}$, $V_{CE} = 300\text{ V}$



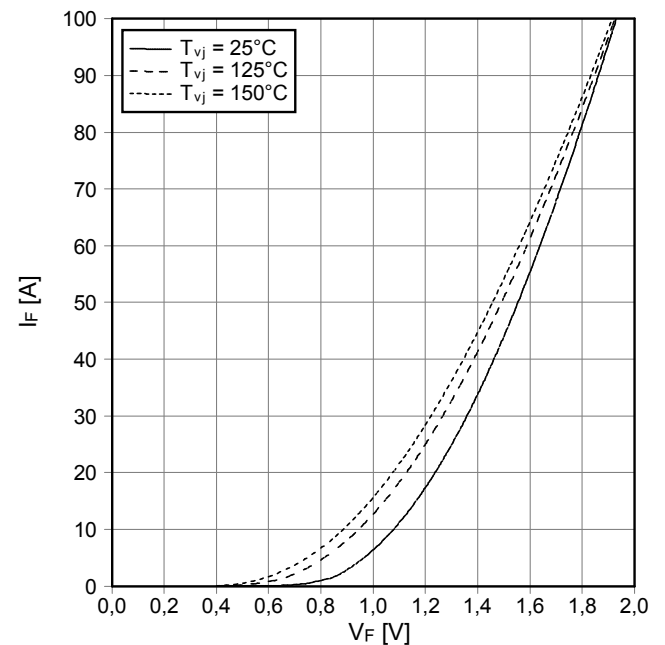
Transienter Wärmewiderstand IGBT-Wechselr.
transient thermal impedance IGBT-inverter
 $Z_{thJH} = f(t)$



Sicherer Rückwärts-Arbeitsbereich IGBT-Wr. (RBSOA)
reverse bias safe operating area IGBT-inv. (RBSOA)
 $I_C = f(V_{CE})$
 $V_{GE} = \pm 15\text{ V}$, $R_{Goff} = 6.8\ \Omega$, $T_{vj} = 150^\circ\text{C}$



Durchlasskennlinie der Diode-Wechselr. (typisch)
forward characteristic of diode-inverter (typical)
 $I_F = f(V_F)$

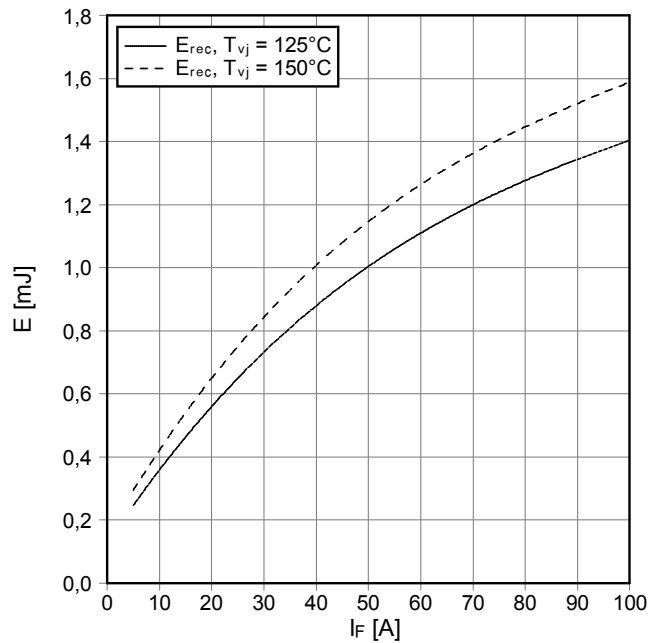


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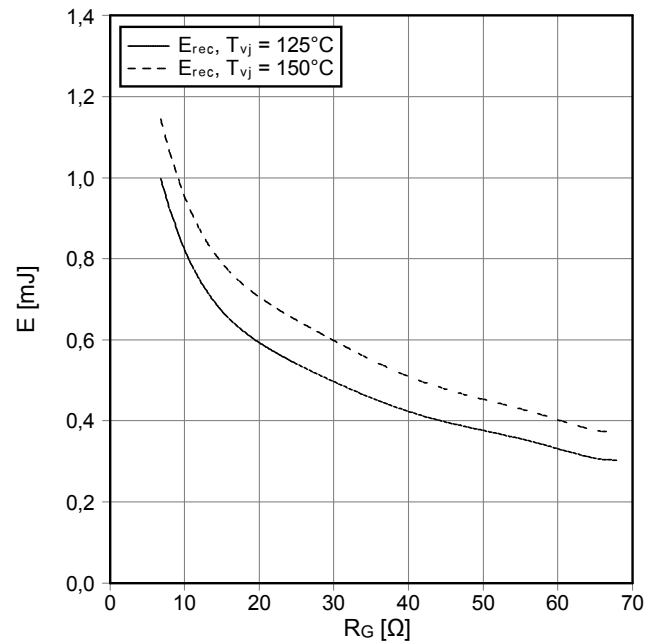
Schaltverluste Diode-Wechselr. (typisch)
switching losses diode-inverter (typical)

$E_{rec} = f(I_F)$
 $R_{Gon} = 6.8 \Omega, V_{CE} = 300 V$



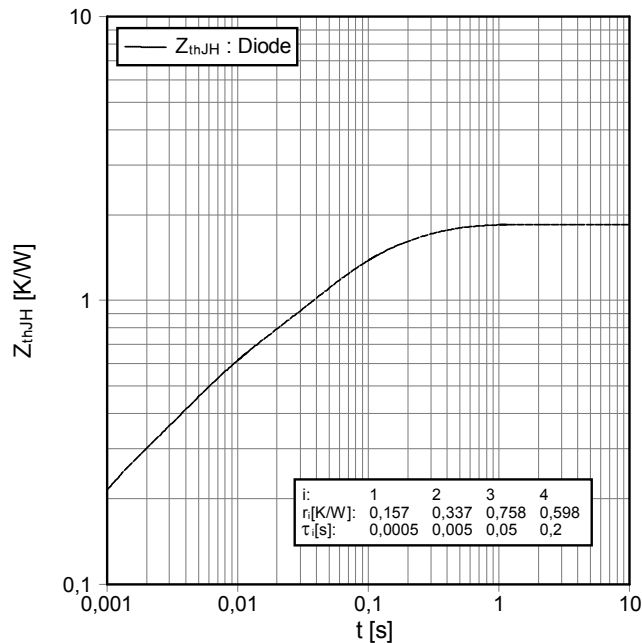
Schaltverluste Diode-Wechselr. (typisch)
switching losses diode-inverter (typical)

$E_{rec} = f(R_G)$
 $I_F = 50 A, V_{CE} = 300 V$



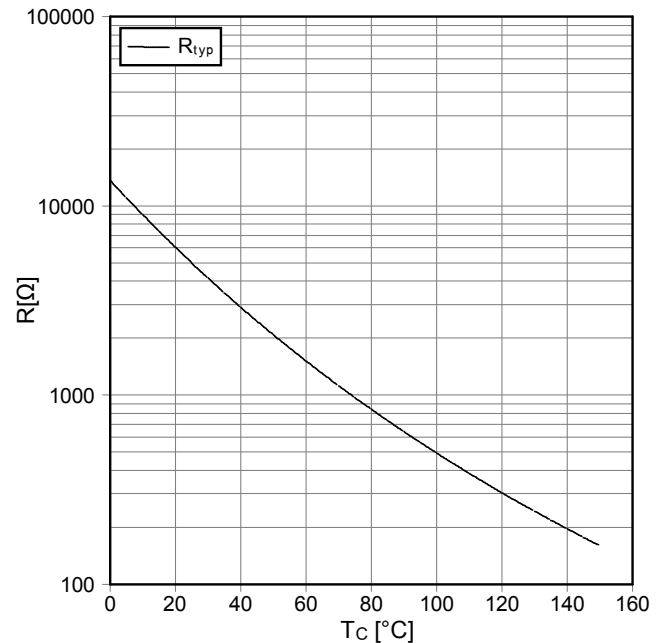
Transienter Wärmewiderstand Diode-Wechselr.
transient thermal impedance diode-inverter

$Z_{thJH} = f(t)$



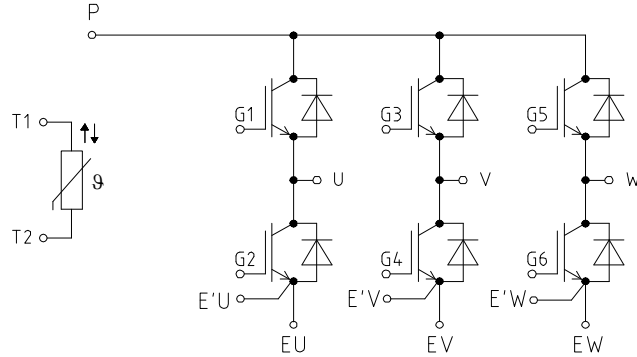
NTC-Temperaturkennlinie (typisch)
NTC-temperature characteristic (typical)

$R = f(T)$

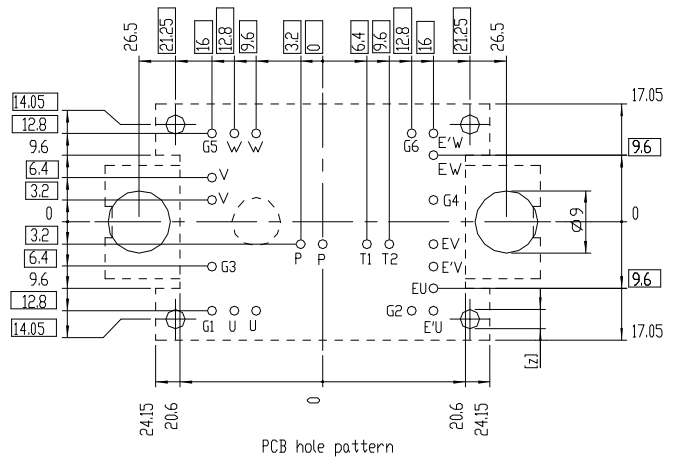
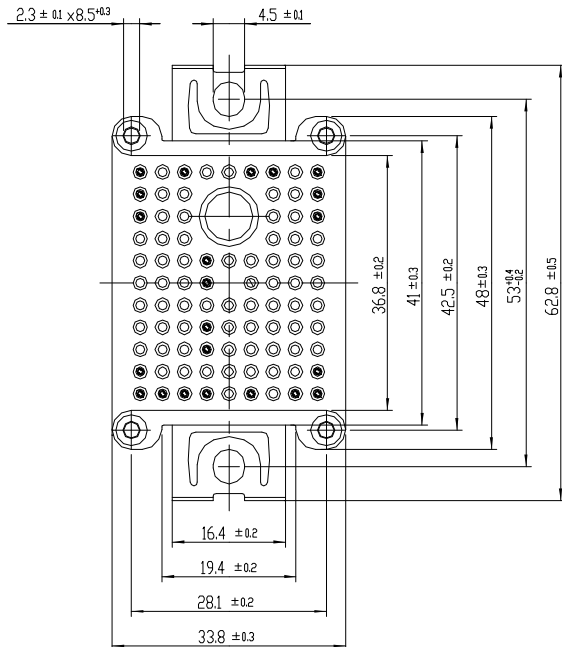
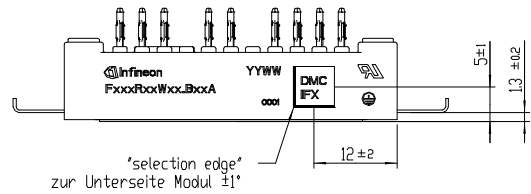
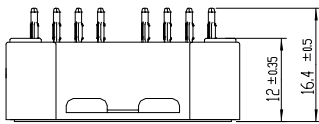


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Schaltplan / circuit diagram



Gehäuseabmessungen / package outlines



- Pin-Grid 3.2 mm
- Tolerance of PCB hole pattern ± 0.1 26x
- Hole specification for contacts see application note Easy PressFIT
- Diameters of drill $\varnothing 1.15$ mm and copper thickness in hole 25 - 50 μ m
- [z] recommended diameter of PCB positioning guiding holes $\varnothing 2.8$ mm

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